New Products

Coming Soon!

Next-Generation High Aspect Ratio DC Acid Copper Plating Process

To address market needs to improve throughput on big and thick printed circuit boards, Dow Electronic Materials is currently testing a new DC acid copper plating product to be release this year. The target is to provide up to 3x the plating rate compared to existing DC acid copper plating processes targeting high aspect ratio boards without sacrificing reliability.

Benefits

- Ideal for panels with up to 16:1 aspect ratio
- Plating through holes up to 0.5 mm in diameter
- No cracks
- Excellent thermal reliability
- Excellent throwing power for boards up to 8 mm thick
- High current density up to 15 ASF
- Long bath life
- Full analysis system

Next-Generation Universal Sweller

A new advanced sweller product provides cost-effective, wide operational window desmearing solutions for both normal and high-performance laminates with reduced toxicity solvent and low concentration chemistry. Bench marking against some of the best performing swellers on the market today, this new advanced sweller is showing superior performance in a number of key areas.

Benefits

- Better roughness
- Shorter process time with N-Tg laminates
- Fewer HWPA defects
- Higher peel strength
- Improved texturing with H-Tg and M-Tg laminates
- Wide process windows

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